URGENT INSTRUCTION SUPPLEMENT
INSTALLATION OF STUD MOUNTED SEMICONDUCTOR DEVICES

1. GENERAL

1.1 It is the intent of this UIS to inform Installation of a change in the heat conductive compound for mounting semiconductor devices.

1.2 BTL advises that all silicone base materials be avoided due to the possibility of open contact contamination. Consequently, the R-3126 silicone based Heat Conductive Compound has been cancelled and replaced with the R-4873, KS-21343 L1 non-silicone based Heat Conductive Compound.

1.3 We do not foresee any contact contamination problems developing due to the semiconductors which have been field mounted with the R-3126 Compound to date. All of the equipment in the vicinity of these semiconductor devices have covered contacts which preclude the chance of silicone contamination. Hence no action is required for the semiconductors mounted with the R-3126 compound.

2. INSTRUCTIONS

2.1 Information of Paragraph 4.1 should be revised to specify the R-4873, KS-21343 L1 non-silicone base Heat Conductive Compound rather than the R-3126 silicone base Heat Conductive Compound which has been cancelled.

Engineering Planning Manager
(Installation)

NOTICE - NOT FOR USE OR DISCLOSURE OUTSIDE THE BELL SYSTEM EXCEPT UNDER WRITTEN AGREEMENT

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